



Final Product Change Notification

202302013F01 : For LPC176x in LQFP100, TFME Will be Added as a 2nd Source Assembly Site

Note: This notice is NXP Company Proprietary.

Issue Date: Feb 27, 2023 **Effective date:** May 28, 2023

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Management summary

For LPC176x in LQFP100, TFME will be added as a 2nd source assembly site.

Change Category

<input type="checkbox"/> Wafer Fab Process	<input type="checkbox"/> Assembly Process	<input checked="" type="checkbox"/> Product Marking	<input type="checkbox"/> Test Process	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab Materials	<input checked="" type="checkbox"/> Assembly Materials	<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Equipment	<input type="checkbox"/> Errata
<input type="checkbox"/> Wafer Fab Location	<input checked="" type="checkbox"/> Assembly Location	<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Location	<input type="checkbox"/> Electrical spec./Test coverage
<input type="checkbox"/> Firmware	<input type="checkbox"/> Other			

PCN Overview

Description

For products LPC176xFBD100, TFME will be added as a 2nd source assembly site.

The assembly materials (mold compound, die attach and bond wire) also change. See the attached self qualification report for details.

Reason

Supply continuity.

Identification of Affected Products

Top Side Marking

The assembly site code is located in the last line of the top side marking. See the attached self qualification report for marking details.

Product Availability

Sample Information

Samples are available upon request

Samples of superset part number LPC1768FBD100 are available.

Production

Planned first shipment May 28, 2023

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Once PCN is effective, customer may receive product from either assembly site.

Additional information

Self qualification: [view online](#)

Additional documents: [view online](#)

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Mar 29, 2023.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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NXP Quality Management Team.

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Changed Orderable Part#	12NC	Product Type	Product Description	Package Outline	Package Description	Product Status	Customer Specific Indicator	Product Line
LPC1766FBD100,551	935287917551	LPC1766FBD100	32-bit ARM M3	(L)QFP100	SOT407-1	RFS	No	BLM1
LPC1766FBD100K	935287917557	LPC1766FBD100	32-bit ARM M3	(L)QFP100	SOT407-1	RFS	No	BLM1
LPC1765FBD100,551	935287918551	LPC1765FBD100	32-bit ARM M3	(L)QFP100	SOT407-1	RFS	No	BLM1
LPC1765FBD100K	935287918557	LPC1765FBD100	32-bit ARM M3	(L)QFP100	SOT407-1	RFS	No	BLM1
LPC1764FBD100,551	935287919551	LPC1764FBD100	32-bit ARM M3	(L)QFP100	SOT407-1	RFS	No	BLM1
LPC1764FBD100K	935287919557	LPC1764FBD100	32-bit ARM M3	(L)QFP100	SOT407-1	RFS	No	BLM1
LPC1768FBD100Y	935288608518	LPC1768FBD100	32-bit ARM M3	(L)QFP100	SOT407-1	RFS	No	BLM1
LPC1768FBD100,551	935288608551	LPC1768FBD100	32-bit ARM M3	(L)QFP100	SOT407-1	RFS	No	BLM1
LPC1768FBD100K	935288608557	LPC1768FBD100	32-bit ARM M3	(L)QFP100	SOT407-1	RFS	No	BLM1
LPC1767FBD100,551	935289808551	LPC1767FBD100	32-bit ARM M3	(L)QFP100	SOT407-1	RFS	No	BLM1
LPC1767FBD100K	935289808557	LPC1767FBD100	32-bit ARM M3	(L)QFP100	SOT407-1	RFS	No	BLM1
LPC1769FBD100,551	935290522551	LPC1769FBD100	32-bit ARM M3	(L)QFP100	SOT407-1	RFS	No	BLM1
LPC1769FBD100K	935290522557	LPC1769FBD100	32-bit ARM M3	(L)QFP100	SOT407-1	RFS	No	BLM1
LPC1763FBD100Y	935291276518	LPC1763FBD100	32-bit ARM M3	(L)QFP100	SOT407-1	RFS	No	BLM1
LPC1763FBD100,551	935291276551	LPC1763FBD100	32-bit ARM M3	(L)QFP100	SOT407-1	RFS	No	BLM1
LPC1763FBD100K	935291276557	LPC1763FBD100	32-bit ARM M3	(L)QFP100	SOT407-1	RFS	No	BLM1
LPC1769FBD100/P1K	935430318557	LPC1769FBD100/P1	32-bit ARM M3	(L)QFP100	SOT407-1	RFS	No	BLM1